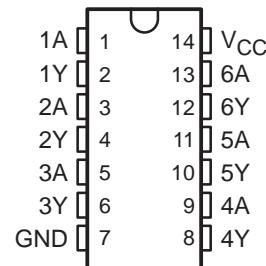


- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Greater Noise Immunity Than Standard Inverters
- Operates With Much Slower Than Standard Input Rise and Fall Slew Rates
- Balanced Propagation Delays
- ± 24 -mA Output Drive Current
 - Fanout to 15 F Devices
- SCR Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

E OR M PACKAGE
(TOP VIEW)



description/ordering information

The CD74AC14 contains six independent inverters. This device performs the Boolean function $Y = \bar{A}$.

Each circuit functions as an independent inverter, but because of the Schmitt action, the inverters have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

ORDERING INFORMATION

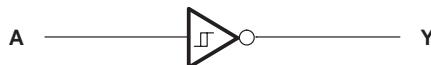
| T _A | PACKAGE [†] | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|----------------------|---------------|-----------------------|------------------|
| -55°C to 125°C | PDIP – E | Tube | CD74AC14E | CD74AC14E |
| | SOIC – M | Tube | CD74AC14M | AC14M |
| | | Tape and reel | CD74AC14M96 | |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each inverter)

| INPUT A | OUTPUT Y |
|---------|----------|
| H | L |
| L | H |

logic diagram, each inverter (positive logic)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

CD74AC14 HEX SCHMITT-TRIGGER INVERTER

SCHS228B – SEPTEMBER 1998 – REVISED MARCH 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|-----------------|
| Supply voltage range, V_{CC} | -0.5 V to 6 V |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) | ± 20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) | ± 50 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 50 mA |
| Continuous current through V_{CC} or GND | ± 100 mA |
| Package thermal impedance, θ_{JA} (see Note 2): E package | 80°C/W |
| | M package |
| Storage temperature range, T_{STG} | -65°C to 150°C |

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

recommended operating conditions (see Note 3)

| | | TA = 25°C | | -55°C to 125°C | | -40°C to 85°C | | UNIT |
|-----------------|---------------------------|----------------------------------|-----------------|----------------|-----------------|---------------|-----------------|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | 1.5 | 5.5 | 1.5 | 5.5 | 1.5 | 5.5 | V |
| V _I | Input voltage | 0 | V _{CC} | 0 | V _{CC} | 0 | V _{CC} | V |
| V _O | Output voltage | 0 | V _{CC} | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 4.5 V to 5.5 V | | -24 | -24 | -24 | -24 | mA |
| I _{OL} | Low-level output current | V _{CC} = 4.5 V to 5.5 V | | 24 | 24 | 24 | 24 | mA |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

CD74AC14
HEX SCHMITT-TRIGGER INVERTER

SCHS228B – SEPTEMBER 1998 – REVISED MARCH 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | -55°C to 125°C | | -40°C to 85°C | | UNIT |
|--|---|---------------------------|-----------------------|------|----------------|------|---------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| V _{T+} Positive-going threshold | | 5 V | 2.6 | 3.4 | 2.6 | 3.4 | 2.6 | 3.4 | V |
| V _{T-} Negative-going threshold | | 5 V | 1.6 | 2.4 | 1.6 | 2.4 | 1.6 | 2.4 | V |
| ΔV _T Hysteresis (V _{T+} – V _{T-}) | | 5 V | 0.5 | | 0.5 | | 0.5 | | V |
| V _{OH} | V _I = V _{T+} | I _{OH} = -50 μA | 1.5 V | 1.4 | 1.4 | 1.4 | | | V |
| | | | 3 V | 2.9 | 2.9 | 2.9 | | | |
| | | | 4.5 V | 4.4 | 4.4 | 4.4 | | | |
| | | I _{OH} = -4 mA | 3 V | 2.58 | 2.4 | 2.48 | | | |
| | | I _{OH} = -24 mA | 4.5 V | 3.94 | 3.7 | 3.8 | | | |
| | | I _{OH} = -50 mA† | 5.5 V | | 3.85 | | | | |
| | | I _{OH} = -75 mA† | 5.5 V | | | 3.85 | | | |
| V _{OL} | V _I = V _{T-} | I _{OL} = 50 μA | 1.5 V | 0.1 | 0.1 | 0.1 | | | V |
| | | | 3 V | 0.1 | 0.1 | 0.1 | | | |
| | | | 4.5 V | 0.1 | 0.1 | 0.1 | | | |
| | | I _{OL} = 12 mA | 3 V | 0.36 | 0.5 | 0.44 | | | |
| | | I _{OL} = 24 mA | 4.5 V | 0.36 | 0.5 | 0.44 | | | |
| | | I _{OL} = 50 mA† | 5.5 V | | 1.65 | | | | |
| | | I _{OL} = 75 mA† | 5.5 V | | | 1.65 | | | |
| I _I | V _I = V _{CC} or GND | 5.5 V | | ±0.1 | ±1 | ±1 | | | μA |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | 4 | 80 | 40 | | | μA |
| C _i | | | | 10 | 10 | 10 | | | pF |

† Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | -55°C TO 125°C | | -40°C TO 85°C | | UNIT |
|------------------|--------------|-------------|----------------|------|---------------|-----|------|
| | | | MIN | MAX | MIN | MAX | |
| t _{PLH} | A | Y | 2.6 | 10.5 | 2.7 | 9.5 | ns |
| | | | 2.6 | 10.5 | 2.7 | 9.5 | |

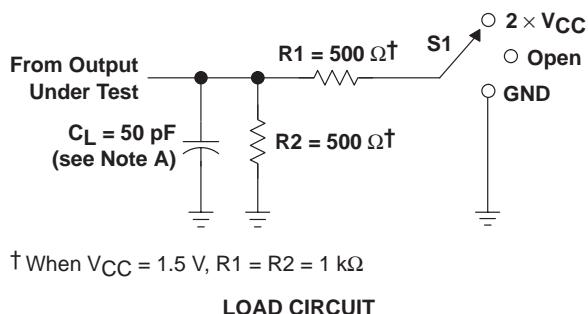
operating characteristics, V_{CC} = 5 V, T_A = 25°C

| PARAMETER | | | TYP | UNIT |
|-----------------|-------------------------------|--|-----|------|
| C _{pd} | Power dissipation capacitance | | 45 | pF |

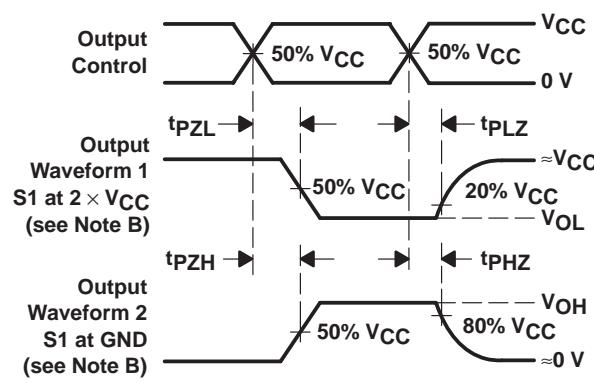
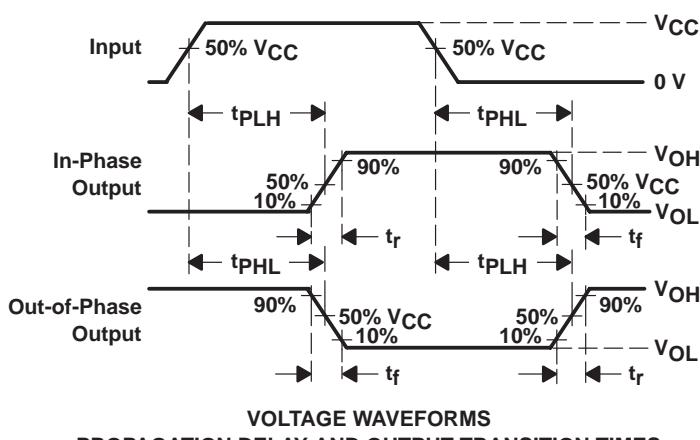
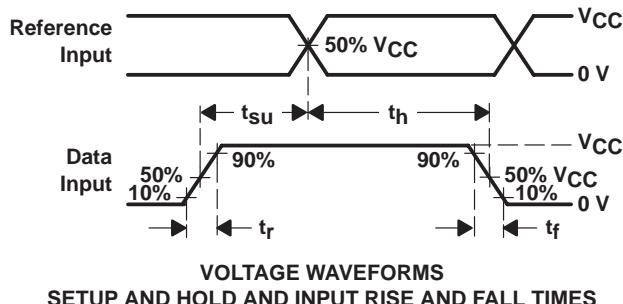
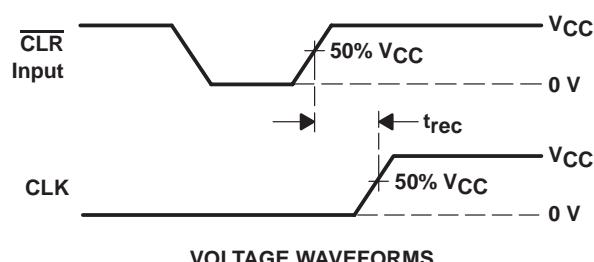
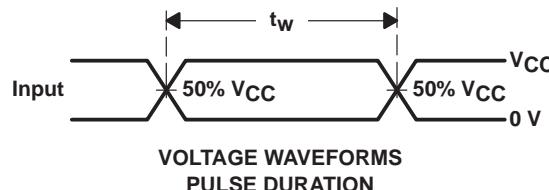
CD74AC14 **HEX SCHMITT-TRIGGER INVERTER**

SCHS228B – SEPTEMBER 1998 – REVISED MARCH 2004

PARAMETER MEASUREMENT INFORMATION



| TEST | S1 |
|-------------------|-------------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | $2 \times V_{CC}$ |
| t_{PHZ}/t_{PZH} | GND |



NOTES:

- A. C_L includes probe and test-fixture capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 3$ ns, $t_f = 3$ ns. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time, with one input transition per measurement.
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. t_{PZL} and t_{PZH} are the same as t_{on} .
- H. t_{PZL} and t_{PZH} are the same as t_{ris} .

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD74AC14E | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74AC14EE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74AC14M | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74AC14M96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74AC14M96E4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74AC14M96G4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74AC14ME4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74AC14MG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

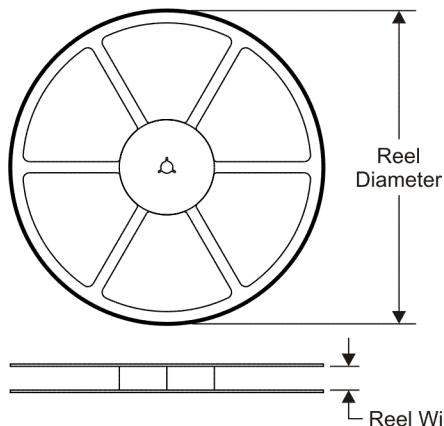
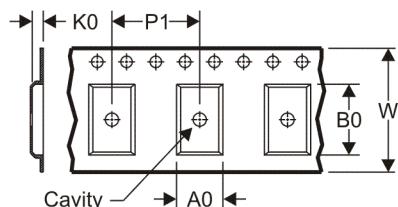
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

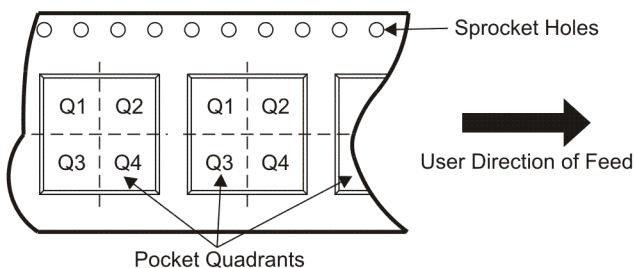
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


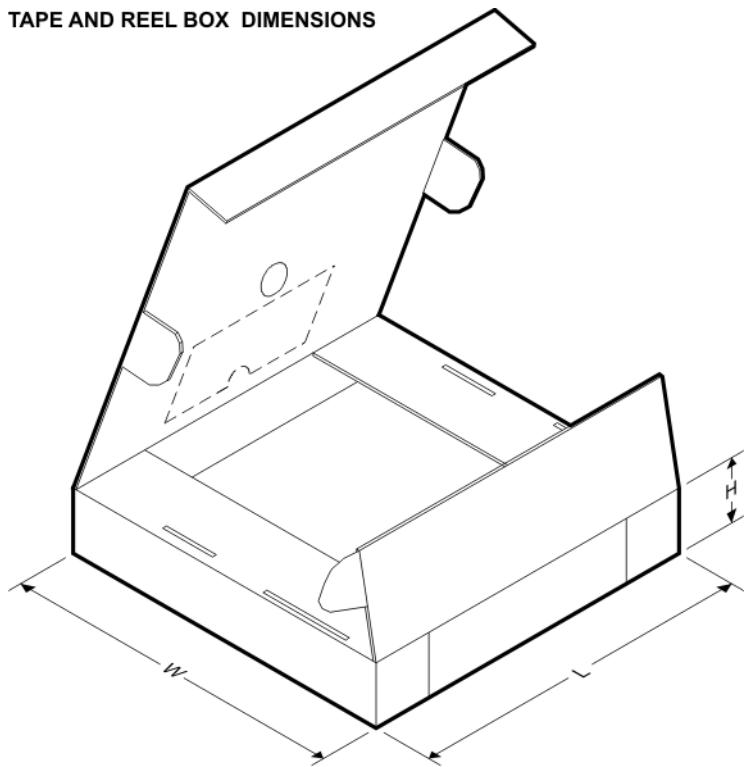
| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74AC14M96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS

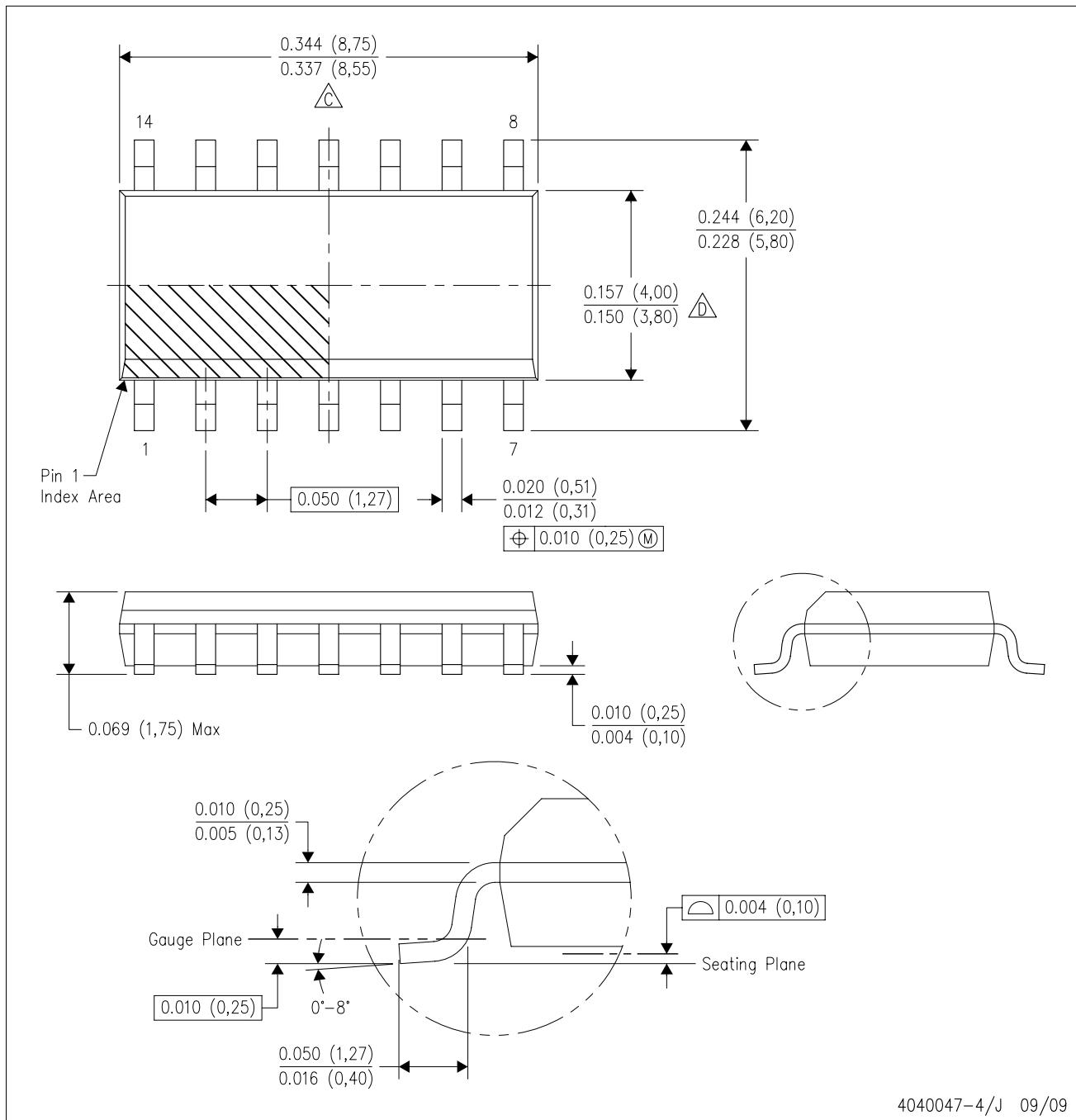


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74AC14M96 | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

